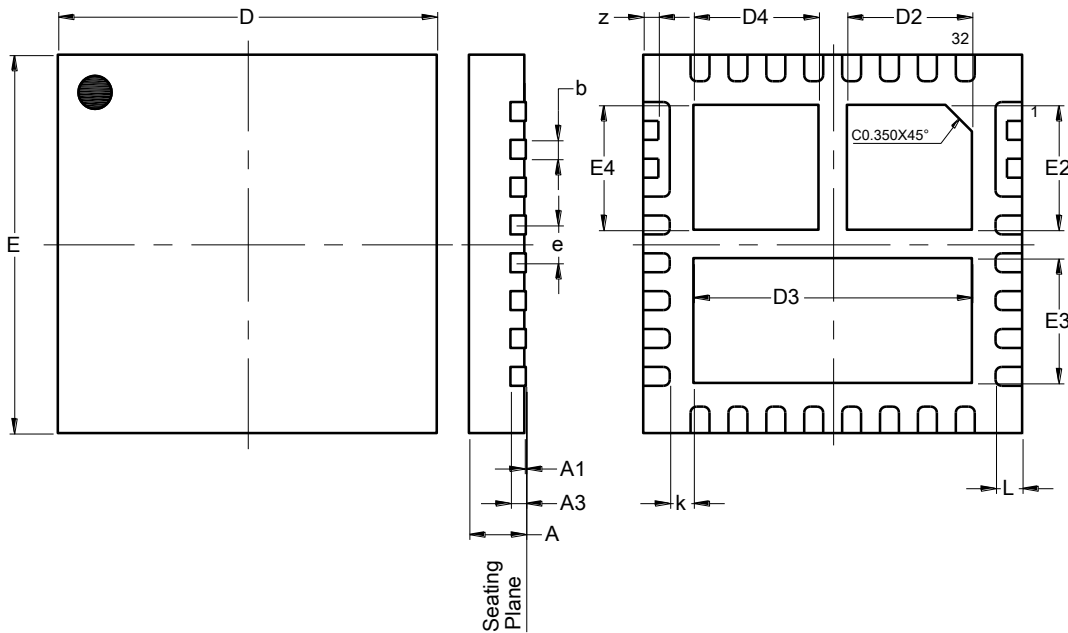


## Package Outline Dimensions

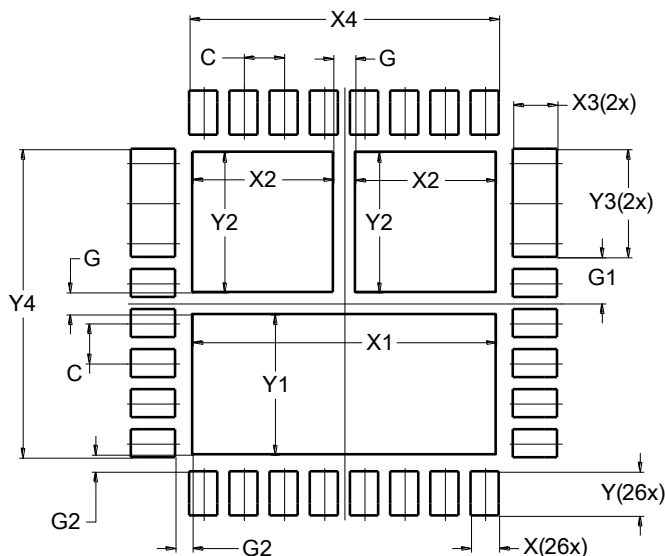
W-QFN5050-32 (Type A1)



W-QFN5050-32 (Type A1)			
Dim	Min	Max	Typ
A	0.70	0.80	0.75
A1	0.00	0.05	0.02
A3	0.203 REF		
b	0.20	0.30	0.25
D	4.90	5.10	5.00
D2	1.60	1.70	1.65
D3	3.63	3.73	3.68
D4	1.60	1.70	1.65
E	4.90	5.10	5.00
E2	1.60	1.70	1.65
E3	1.60	1.70	1.65
E4	1.60	1.70	1.65
e	0.50 BSC		
L	0.30	0.40	0.35
k	0.20	--	--
z	0.20 REF		
All Dimensions in mm			

## Suggested Pad Layout

W-QFN5050-32 (Type A1)



Dimensions	Value (in mm)
C	0.500
G	0.275
G1	0.575
G2	0.2125
X	0.350
X1	3.775
X2	1.750
X3	0.550
X4	3.850
Y	0.550
Y1	1.750
Y2	1.750
Y3	1.350
Y4	3.850

### ALL DIMENSIONS ARE NOMINAL VALUES SHOWN IN MILLIMETERS

Note: The suggested land pattern dimensions have been provided for reference only, as actual pad layouts may vary depending on application. These numbers may be modified based on user equipment capability or fabrication criteria. A more robust pattern may be desired for wave soldering and is calculated by adding 0.2 mm to the 'Z' dimension. For further information, please reference document IPC-7351A, Naming Convention for Standard SMT Land Patterns, and for International grid details, please see document IEC, Publication 97.